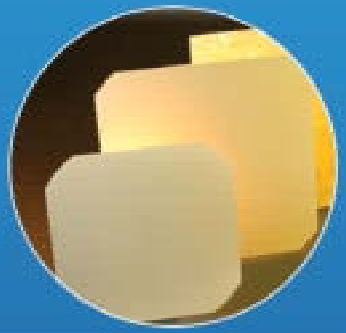
中美矽晶製品股份有限公司



SAS Investors Conference

August 30, 2011

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SAS does not warranty their accuracy, reliability and completeness. There are a number of factors such as economic conditions, firms abilities, industry environment that could cause actual results and developments to differ materially from those expressed or implied by forward looking statements. Investors should not place undue reliance on them.

2011 H1 Key Financial Figures

	NT$K	
Revenue	11,161,615	100%
Gross Profit	2,030,976	18.20%
Operating Profit	1,458,247	13.06%
Net Profit before Tax	1,465,689	13.13%
Net Profit after Tax	1,250,859	11.21%
EPS	3.05	

Current Ratio	164.85%
Debt Ratio	40.49%

NT$M

	H1 2010	H1 2011	YoY Growth%
Revenue	9,524	11,162	17.20%
Gross Profit	1,710	2,031	18.78%
Net Profit B/T	1,197	1,466	22.48%

11'Q2 Business Dynamics

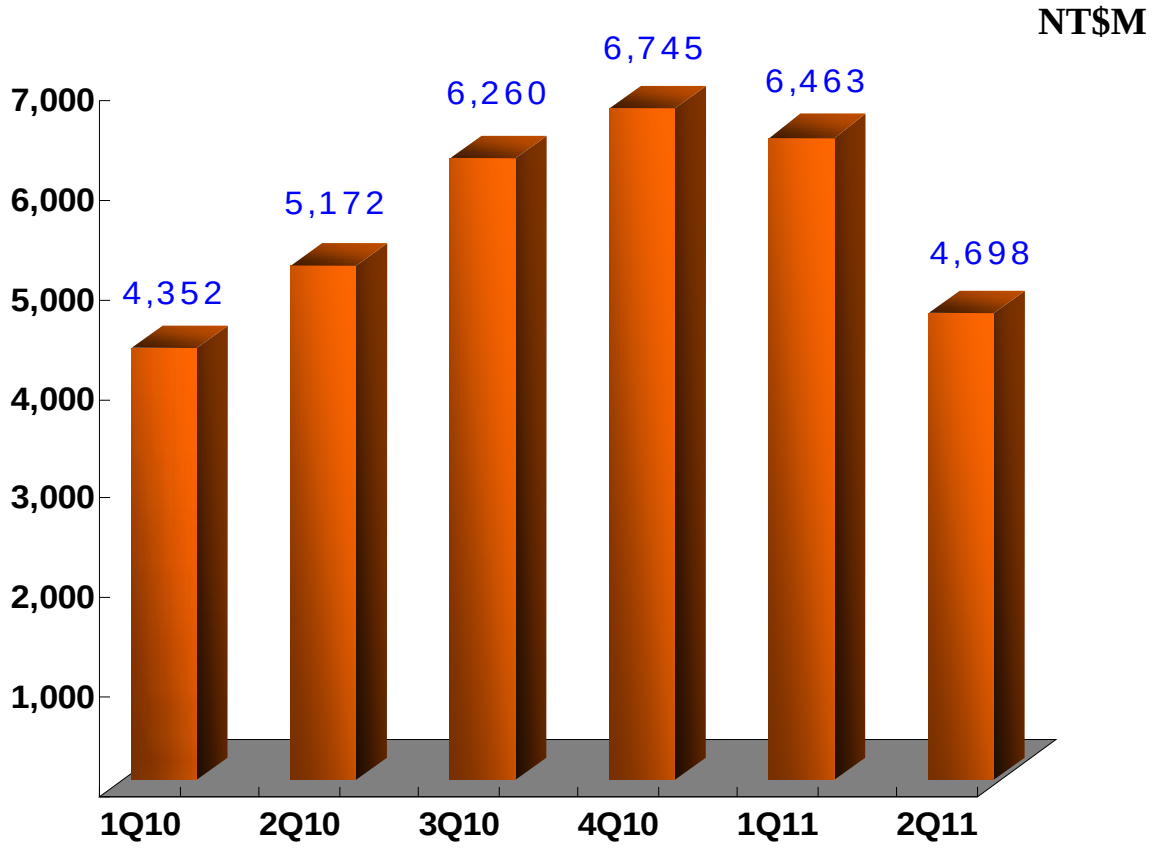
Solar Wafer	• Unexpected market demand plunge with ASP sharp erosion due to Italy and Germany gloomy forecast trigger industry oversupply concern to weigh on revenue. • Contract poly price remain high eroded profitability. • Solar capacity expansion plan put on hold till better market visibility.
Semiconductor Wafer	• Stable Gross margin. • Demand stayed mildly grew. • On-going Epi/Polishing capacity expansion.
Sapphire Wafer	• ASP erosion range escalated resulted from sluggish LED end market performance. • Capacity upgraded to 150K pcs/month, shipment accordingly increased however ASP cut weighed on the revenue to be flat in Q2. • Strengthening R&D efforts in next generation high-brightness wafer development.

Sharp Solar ASP Erosion

In USD	2011/03/09	2011/08/17	↓ %
Polysilicon(per KG)	78.1	51.51	34%
6”Multi Wafer	3.72	2.007	46%
6” Mono Wafer	3.92	2.603	34%
Solar Cell(per Watt)	1.27	0.751	41%

Source: Energy Trend

Quarterly Revenue Trend



2H11 Market Outlook

- Q3 PV demand bounced back to healthy level led to trigger solar ASP edging up.
- Lower Poly cost expected as more capacity would be on line from Q4.
- Weaker Semi wafer momentum resulted from global economy uncertainty.
- Sapphire substrate still suffered from low market visibility, ASP could dip further in next months.

Covalent acquisition

Transaction Overview

Transaction Description	• Covalent Materials Corporation ("Covalent Materials") will transfer all relevant wafer assets to Covalent Silicon Corporation • SAS and Covalent Materials announced a definitive agreement for SAS to buy all ordinary shares issued by Covalent Silicon Corporation from Covalent Materials
Rationale	• Enhanced global market position • Complete product offering • Acquire cutting-edge semiconductor wafer technology • Strengthen tier-1 customer base • Potential synergies
Expected Timing	• Transaction is expected to close by end of 2011 subject to relevant EGM and regulatory approvals

Journey to a Global Wafer Leader

SAS Historical Sales Trend

(USD in Millions)

2000
Kunshan Sino Silicon plant began mass production

2005, 2006
SSC1 founded in Chunan – Expansion of PV wafer business

2007
Expansion of LED sapphire business at Chunan

2008
Acquisition of 100% of GlobiTech to strengthen epitaxial wafer offerings

2008, 2009
Investment of 15% stake and completed 9 solar farms in Italy

2010
JV Partnership

2010
Invested in 23.9% stake

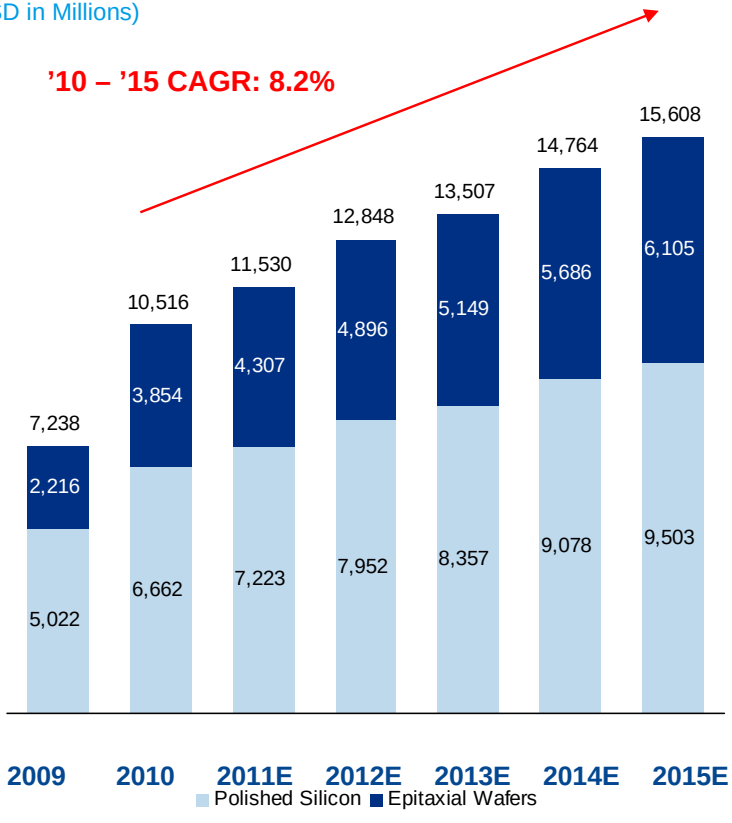
2011
100% acquisition

(1) Bloomberg consensus estimate
(2) Pro Forma revenue based on SAS Bloomberg estimate plus Covalent Silicon FY2011A (fiscal year ended March 31, 2011) revenue of $505mm.

Steady Silicon Wafer Industry Outlook

Silicon Wafer Market Revenue Forecast

(USD in Millions)



Source: Gartner
Note: MSI = millions of square inches
Number of Implied unit price is per square inch data

End Market Growth Forecasts

	Market Growth Forecast
NAND Flash Memory	CAGR: **13.5%** (2009-2015E)
DRAM Memory	CAGR: **12.3%** (2009-2013E)
Logic IC	CAGR: **8.3%** (2009-2014E)
Power Device	CAGR: **11.5%** (2009-2015E)

Covalent Silicon

Covalent Materials

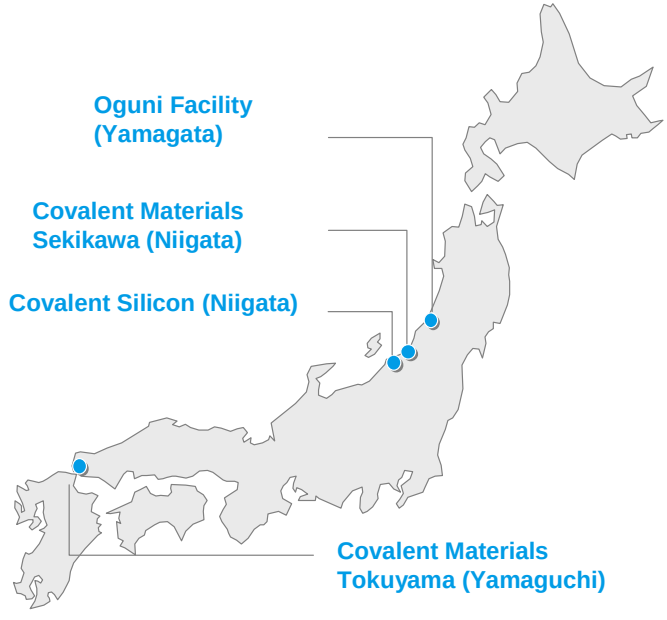
- Formerly known as Toshiba Ceramics, Covalent Materials Corporation (“CV”) was established in 1968 through the merger of Toshiba Denko and Toshiba Internal Insulation
- In October of 2006, Carlyle Japan and Unison Capital launched a tender offer as part of the MBO
- Business Portfolio includes ceramics and wafer business

Carved-out Covalent Silicon

- Top tier manufacturer of specialty wafers globally
- Main products: 300mm wafers, 200mm wafers, Epitaxial wafers, and Diffused wafers
- Employees: 1,442
- Industry leading wafer technology
- Strong global blue chip customer base

Manufacturing and Distribution Sites

- Japan: 4 manufacturing sites
  Niigata, Oguni (Yamagata), Tokuyama (Yamaguchi), Sekikawa (Niigata)
- Overseas: 6 sales offices
  San Jose, Dallas (both US), Munich (Germany), Seoul (Korea), Shanghai (China), Hsinchu (Taiwan)



(1) Excludes loss on sales and disposal of inventory, valuation loss of inventory, and solar wafers/ small diameter wafers related results as Covalent Silicon ceased the business since April 2010.
Note: JPY:USD exchange rate of 81.5:1 is used.

Global Manufacturing Sites

USA TX Factory (GTI)

Kunshan Factory

Headquarters / Hsinchu

Chunan Factory (SSC1、SSC2)

COVALENT

Sapphire factory

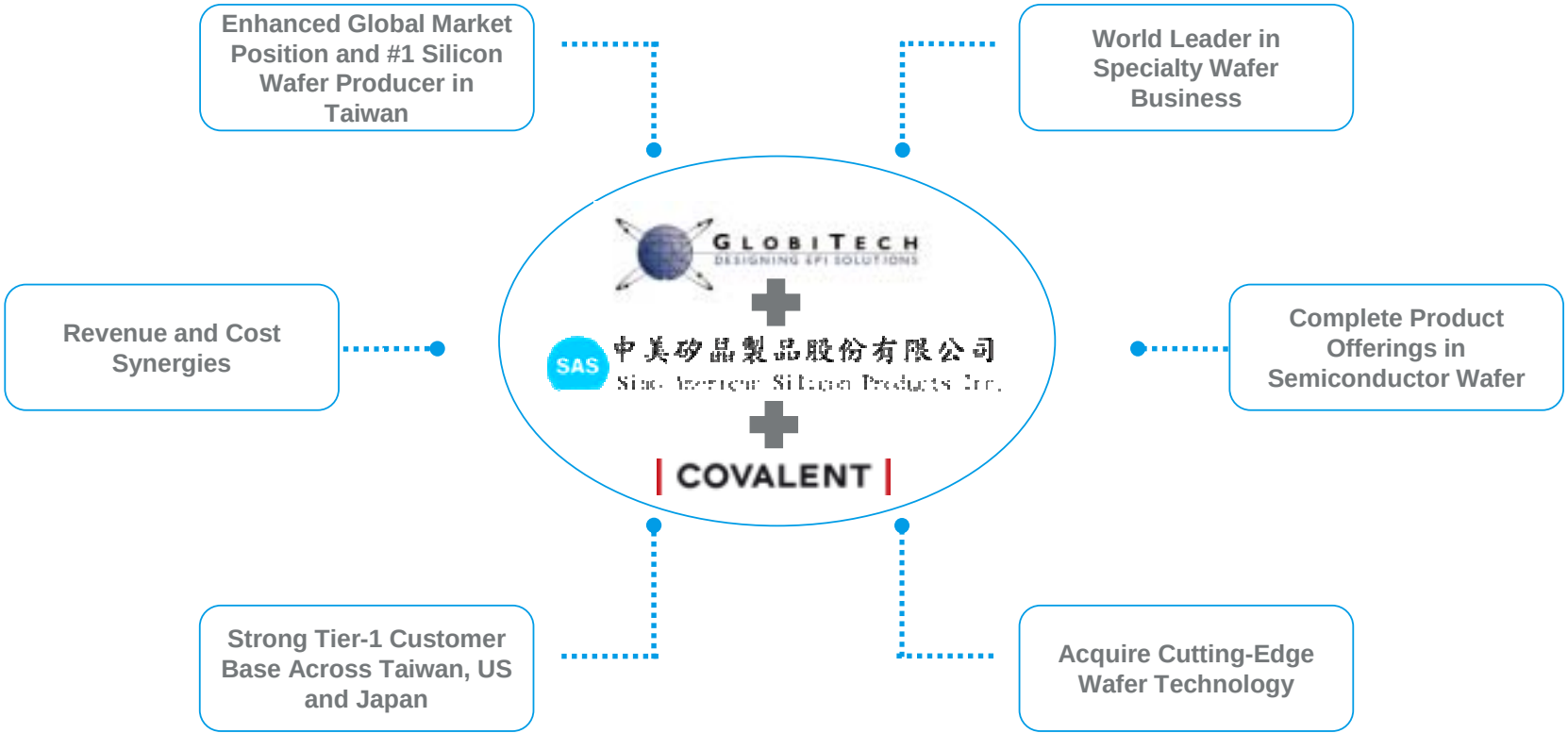
Factory dedicated to sapphire products including ingots and substrates manufacturing

Covalent Product Portfolio

Location	Since Year	Land Size (m^2)	Employees	Capacity	Size	Wafers				
						Polished	Engineered	Epitaxial	Diffused	SOI
Covalent Silicon (Niigata)	1991	137,965	855	200mm: 320kp/M 300mm: 185Kp/M	200mm	✓	✓			
					300mm	✓	✓			
Covalent Materials Tokuyama	1982	4,303	279	185Kp/M	100mm			✓		
					125mm			✓		
					150mm			✓		
					200mm			✓		
Covalent Materials Sekikawa (Niigata)	1985	17,853	169	122Kp/M	100mm				✓	✓
					125mm				✓	✓
					150mm				✓	✓
Oguni Facility	1977	26,672	99	200Kp/M (ingot only)	≤200mm	Single crystal ingots for 200mm and small diameter wafers				

Creates a Global Leader in Wafer Business

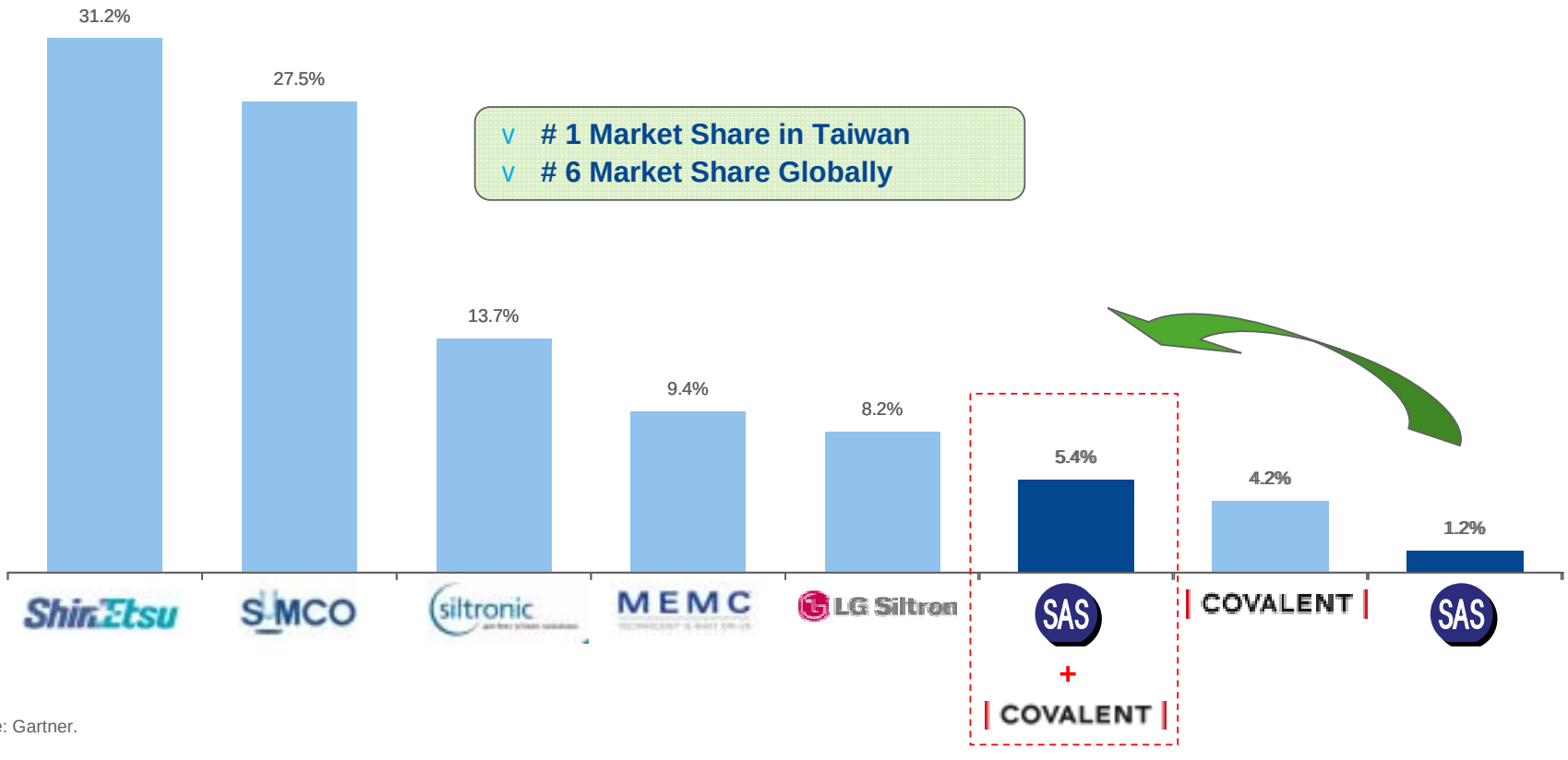
- Creates a leading global wafer manufacturer with strong presence in all solar, semiconductor and LED wafer segments
- Operations span across global semi manufacturing hubs in Taiwan, China, US and Japan



Rationale: Enhanced Global Market Position (Cont'd)

2010 Worldwide Merchant Silicon & Epitaxial Wafer Market Share

Post-Transaction



- # 1 Market Share in Taiwan
- # 6 Market Share Globally

Source: Gartner.

Rationale: Enhanced Global Market Position

Enhances Global Leading Position in Wafer Manufacturing through Added Capacity

- ***185Kp/M*** epitaxial wafer, ***122Kp/M*** diffused wafers for automotive application and SOI wafer, ***320Kp/M*** 200mm polished wafers and annealed wafer, ***185Kp/M*** 300mm polished and annealed wafers

Expands SAS Leadership in Specialty Wafer Product Markets

- Positions SAS to become a ***leader in epitaxial wafers*** and **diffused wafers** for middle-voltage semi-products globally, on top of SAS Globitech's existing ***leading 6'' epitaxial wafer production***

Strengthens Focus on Attractive Power IC Semiconductor Segment

- Both are focused on ***8 inch*** and below wafer products used in attractive power IC applications, which requires higher customization of wafer specification

Becomes the Dominant #1 Wafer Manufacturing Company in Taiwan

- Fills the gap in Taiwan where there are few local upstream wafer manufacturers with scale comparable to international competitors despite many well-known multinational semi companies such as TSMC, UMC & ASE

Rationale: Complete Product Offerings

Complementary Product Offerings in Semiconductor Wafer

中美矽晶製品股份有限公司
Sino-American Silicon Products Inc.

≤150mm wafers

Sensor

Discrete

Analog & Power

MEMS

GLOBITECH

150mm wafers

200mm wafers

Epi

COVALENT

200mm wafers

300mm wafers

Memory

Logic

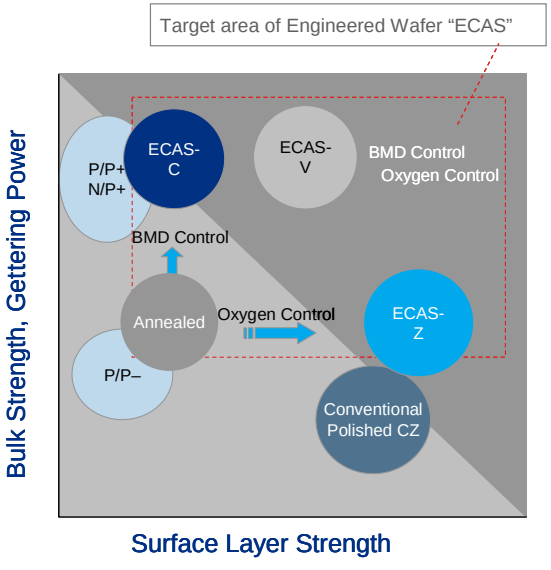
SAS + Globitech: Current Product Offering

SAS + Globitech + Covalent Silicon: Broader and Complete Product Offering

Acquire Cutting-Edge Technology

Superior Technology

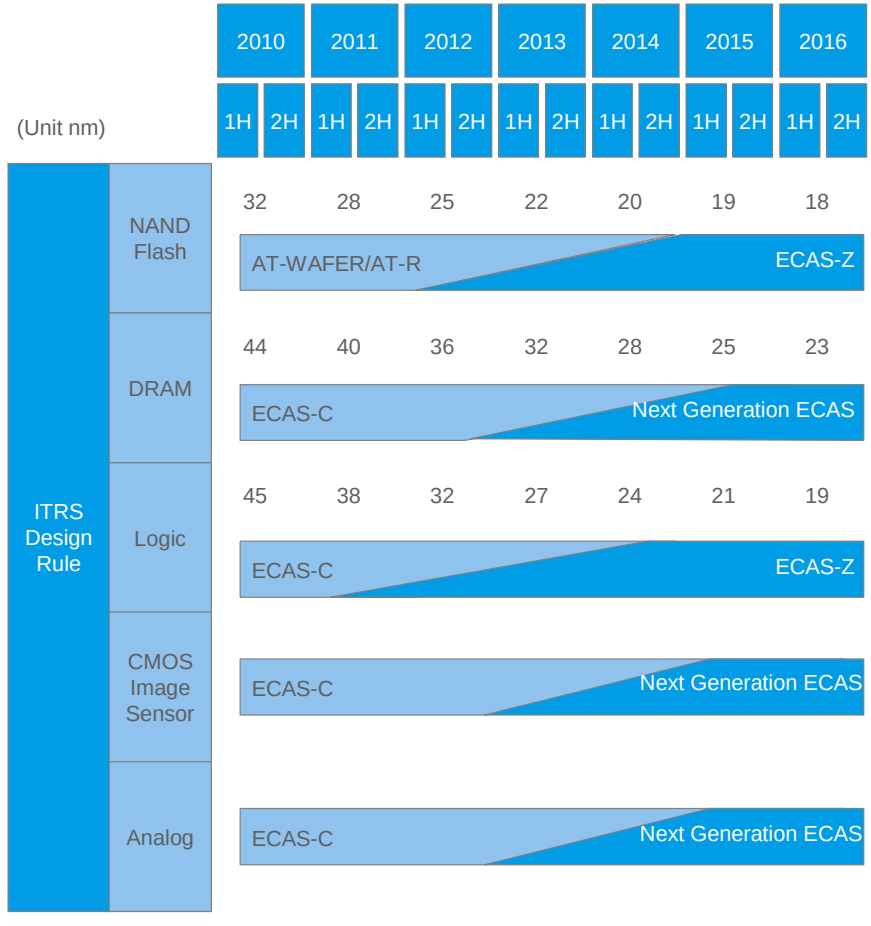
Product Concept of Engineered Wafer



Covalent Wafer Business Core Technology

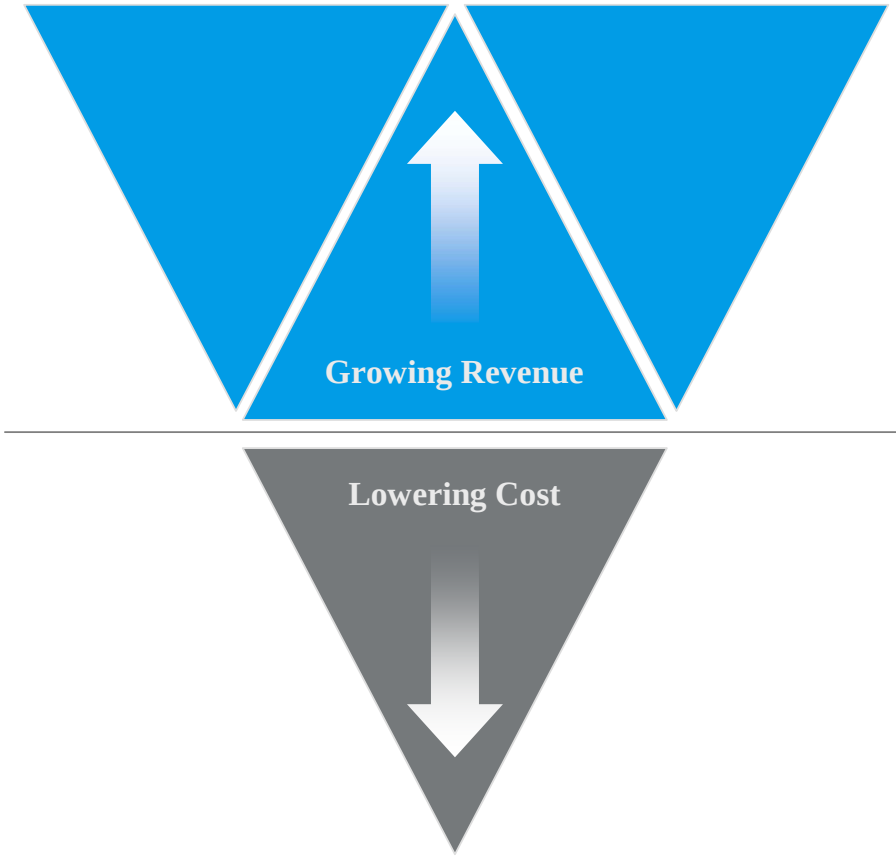
MOS	DIS
●BMD Control ●COP Control	●Defect Control ●Resistance Control
●Surface Oxygen Control	●DW Diffusion/Processing ●Uniformity Technology for Epi ●Resistance Control Technology of Heavy Dope Crystallization

Covalent Wafer Business Technology Roadmap



Rationale: Potential Synergies

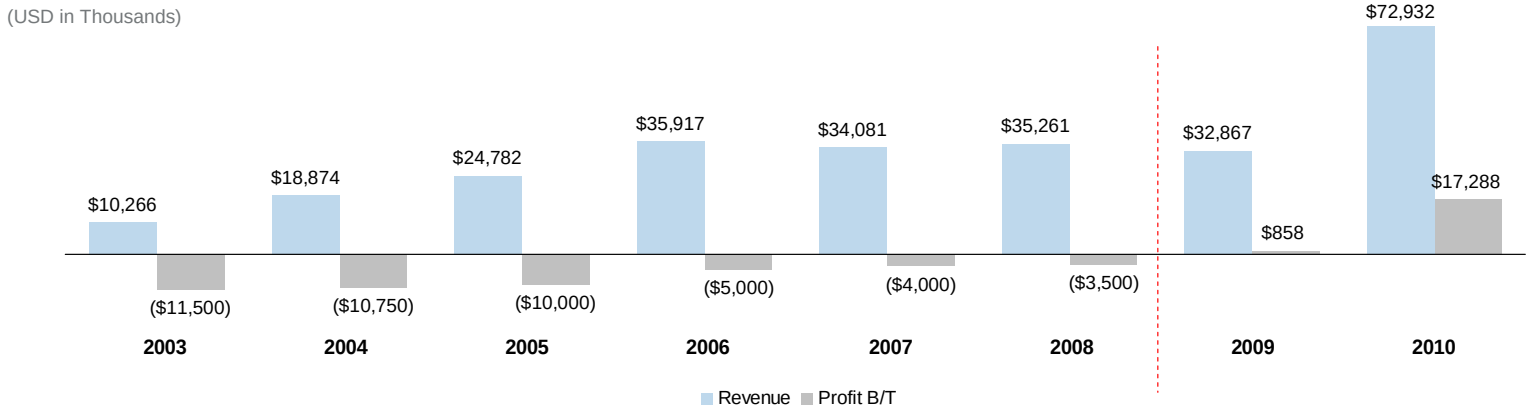
中美矽晶製品股份有限公司 Sino-American Silicon Products Inc. | COVALENT



- **Revenue Synergies:**
  - Realign customers for better profitability
  - Geographical diversity
  - One-stop shop / Cross-selling
  - Increase ASP through joint facilities / optimization
  - Scale and stability to attract customers

Well Planned Integration Scheme

- SAS has extensive experience in successfully integrating cross border acquisitions. In 2008, SAS acquired Globitech and successfully turned the company around from consistent loss-making to profitable in 1 year



- Existing structure of Covalent Silicon will remain largely in place and be integrated into SAS as a team. We expect all operations will by and large remain the same and teams from both sides to work together closely in defining and developing future product roadmap and technologies

- Significant integration planning has already taken place with respect to the acquisition of Covalent Silicon

Transaction Summary Highlights

Enhanced Global Market Position

Complete Product Offerings

Acquire Cutting-Edge Technology

Strengthened Tier-1 Customer Base

Potential Synergies

GLOBITECH
DESIGNING EPI SOLUTIONS

+

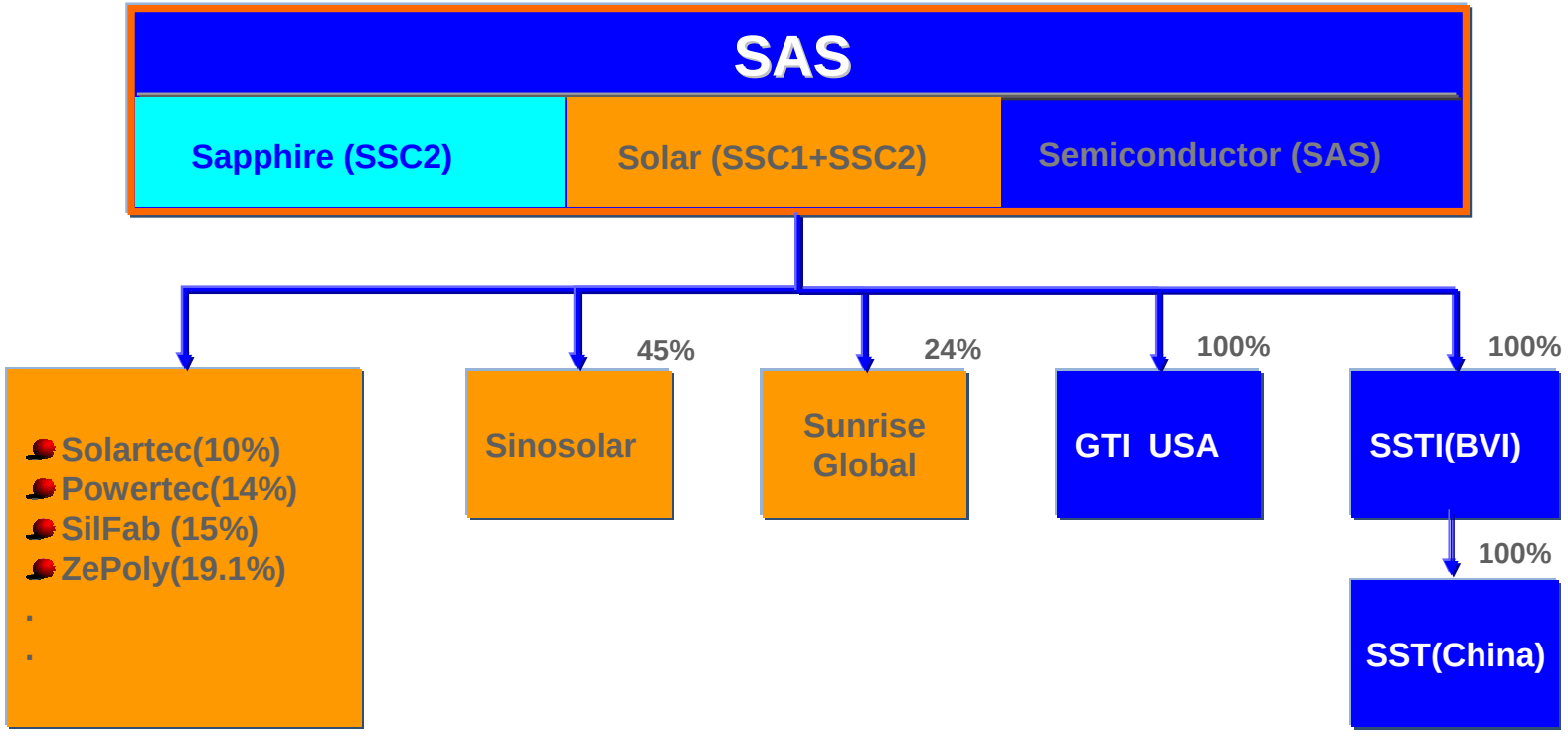
SAS 中美矽晶製品股份有限公司
Sino-American Silicon Products Inc.

+

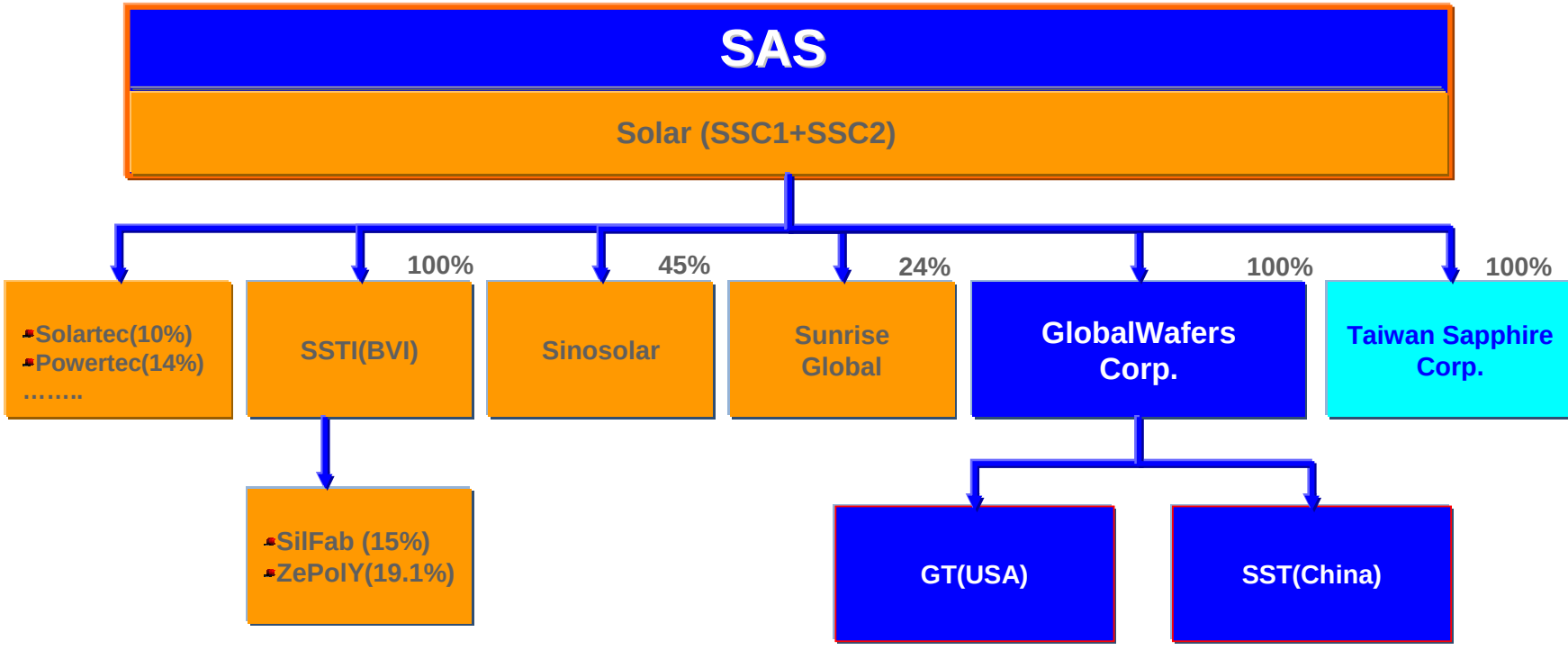
COVALENT

SAS Restructuring after Covalent acquisition

Current holding structure

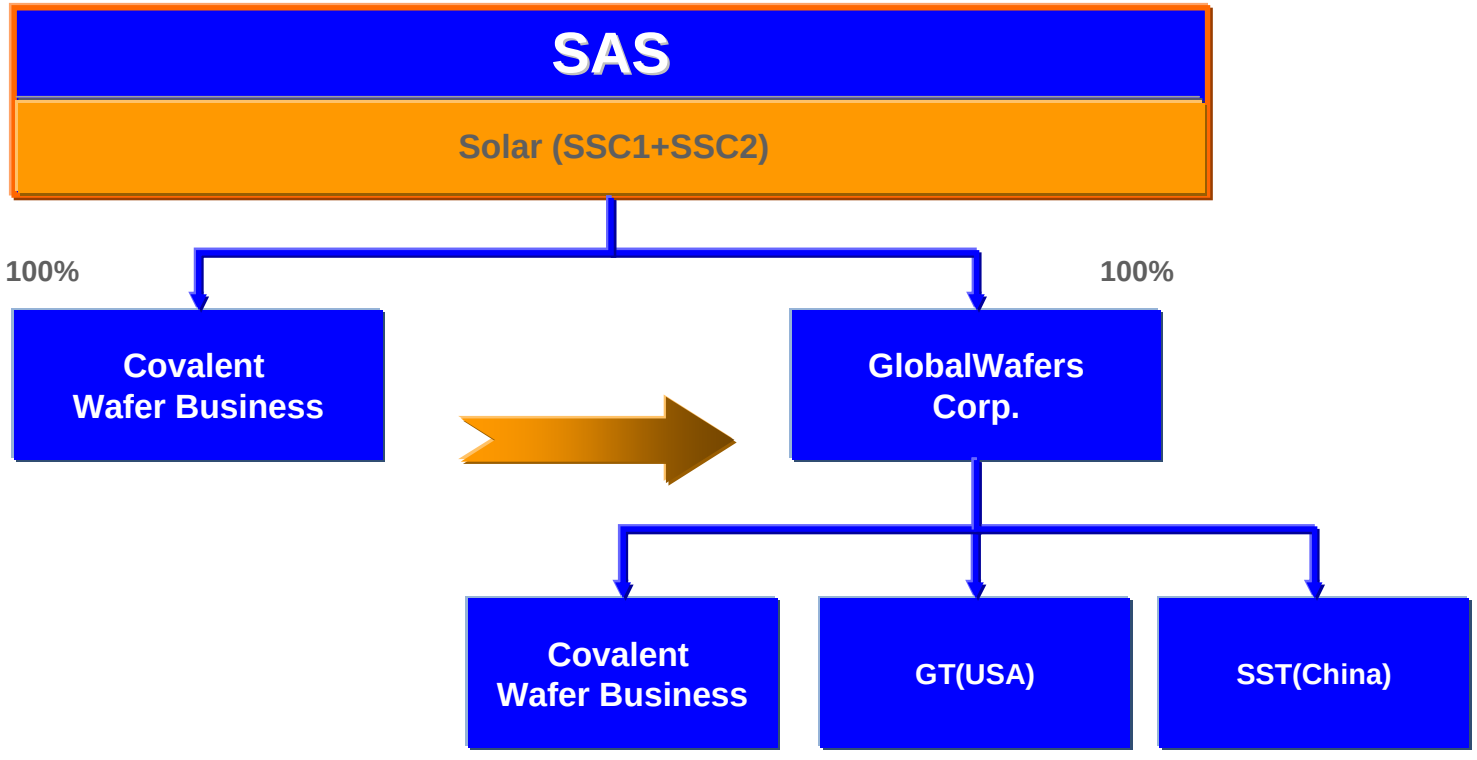


Restructuring



Spin-off target date: 2011/10/01

Future Semiconductor Business Integration



Q&A